

OL-PCF8523U

Bare die; 12 bumps (6-6); 1.58 x 2.15 x 0.22 mm

10 February 2016

Package information

1. Package summary

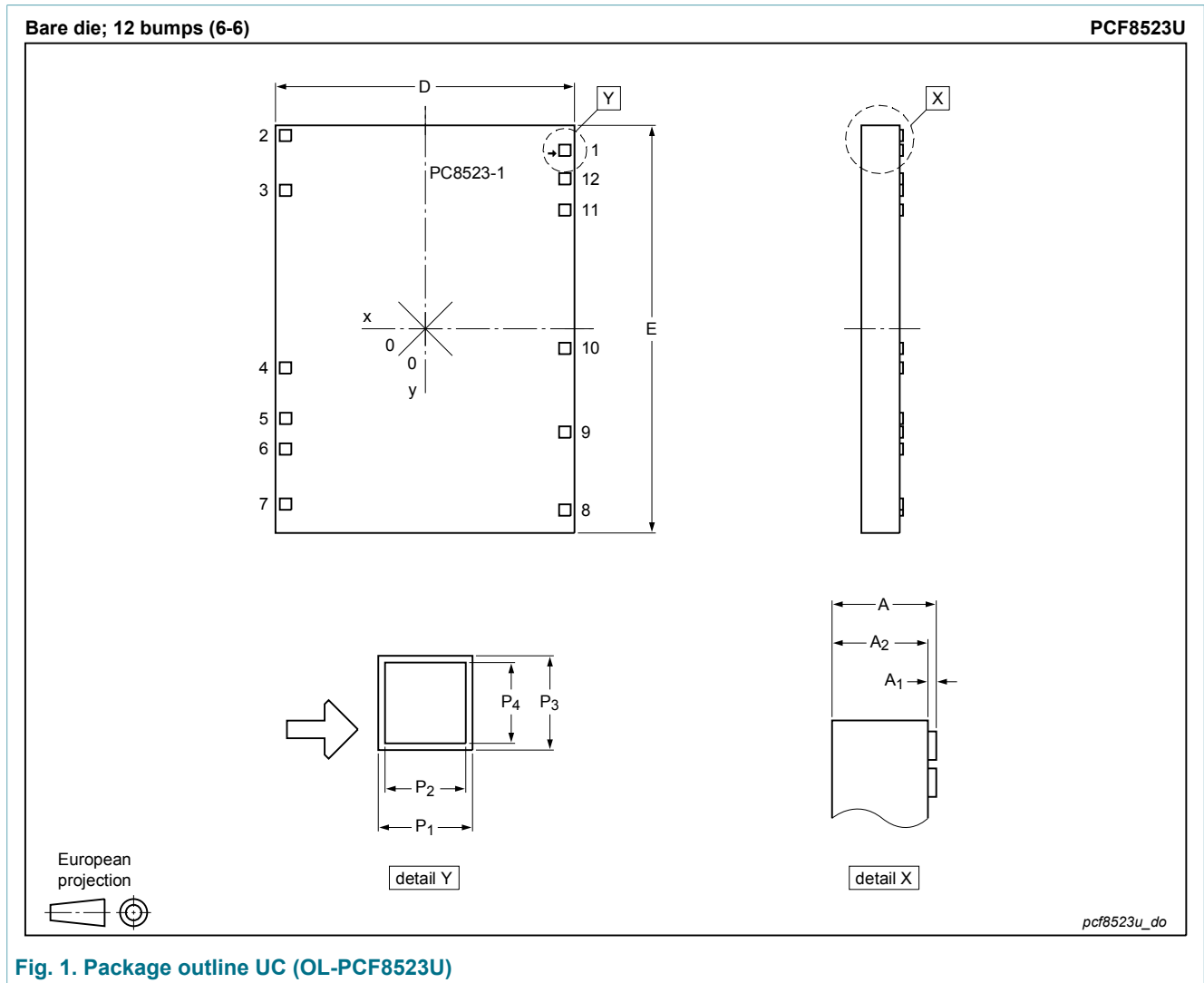
Terminal position code	U (upper)
Package type descriptive code	UC
Package type industry code	UC
Package style descriptive code	UC (uncased chip)
Package style suffix code	NA (not applicable)
Package body material type	X (other)
Mounting method type	S (surface mount)
Issue date	27-9-2010

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	[tbd]	-	1.58	[tbd]	mm
E	package width	[tbd]	-	2.15	[tbd]	mm
A	seated height	[tbd]	-	0.22	[tbd]	mm
A ₂	package height	[tbd]	-	0.2	[tbd]	mm
e	nominal pitch	-	-	0.149	-	mm
n ₂	actual quantity of termination	-	-	12	-	



2. Package outline



3. Legal information

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4. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	3

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